

SO8-FL



Features

- ▶ Thin and thermally enhanced package, the same size as SOIC 8 ld
- ▶ Dual Cu Clip interconnect for better heat dissipation efficiency
- ▶ Clip + wire and multiple wire options are also available
- ▶ Turnkey with test and packing services
- ▶ Green materials: Pb-free plating & halogen free mold compound

New Developments

- ▶ Dual-side exposed pad for better thermal performance
- ▶ Thin wafer dicing with narrow saw streets
- ▶ Larger/higher density leadframe strips
- ▶ Environmentally friendly Pb-free solder paste

Process Highlights

- ▶ Bare copper leadframe with no plating
- ▶ Die attach: 55 μm thin die pick up capability
- ▶ Interconnect: Cu clip technology for better electrical and thermal performance. Also available with clip + wire and multiple wire options.
- ▶ Plating: 100% matte Sn
- ▶ Marking: Pen type laser

SO8-FL (Flat Lead) is a thinner and thermally enhanced package, improving power dissipation capability by 47%, while maintaining the same footprint area (5 x 6 mm) as standard SOIC 8 ld packages. This package is available in both JEDEC and JEITA package outlines.

This package may also be know as:

- ▶ SOP-Adv
- ▶ PowerFLAT 5x6
- ▶ TDSON
- ▶ HVSON
- ▶ JEDEC MO-240 AA

Applications

SO8-FL is suitable for medium-power applications, designed for low on-resistance and high-speed-switching MOSFETs:

- ▶ Battery protection circuits
- ▶ Notebook PCs
- ▶ Portable electronic devices
- ▶ DC-DC converters

Reliability Qualification

Amkor devices are assembled with proven reliable semiconductor materials.

- ▶ All tests include pre-condition of: Ta = 85°C/RH = 85%, 72 hrs with IR reflow, Ta = 265°C, 3X
- ▶ High Temperature Storage, Ta = 150°C, 1000 hrs
- ▶ Pressure Cooker, Ta = 121°C/RH = 100%/P = 2 atm, 96 hrs
- ▶ Temperature Cycle, -65~150°C, 300 cycles

Test Service

Amkor offers full turnkey business for all power discrete products, with the capability to test various types of power devices including MOSFETs, bipolar transistors, IGBTs, diodes and regulator ICs/intelligent power devices,

- ▶ Amkor power discrete test capability:
 - ▷ Static test (DC)
 - ▷ Dynamic test (AC, Switching/Trr, Capacitance/Rg)
 - ▷ Destruction test (Inductive load/VSUS, I Latch, Surge, Isolation/VIL)
 - ▷ Thermal Resistance (ΔVDS , ΔmV , etc.)
- ▶ Program generation/conversion
- ▶ Failure analysis
- ▶ Available test/handling technology
- ▶ Integrated marking, vision inspection and tape & reel services

SO8-FL

Standard Materials

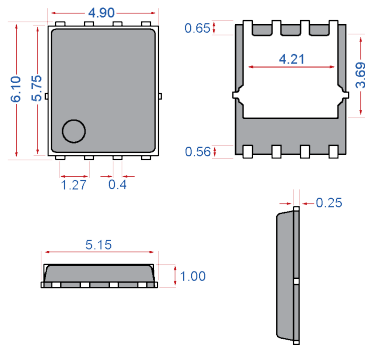
- ▶ Leadframe: Bare copper
- ▶ Die attach: Solder paste
- ▶ Interconnect (3 options):
 - ▷ Dual Cu clips
 - ▷ Multiple Cu wires
 - ▷ Cu clip + 1 gate wire
- ▶ Mold compound: Halogen free

Shipping

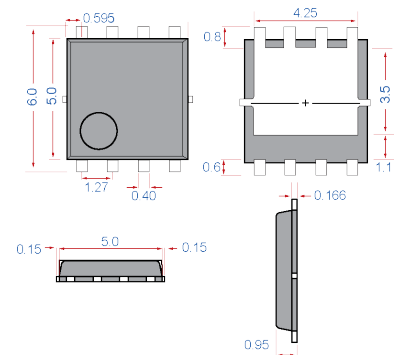
- ▶ Tape and reel packing
 - ▷ 3000 pcs per reel (JEDEC)
 - ▷ 5000 pcs per reel (JEITA)
 - ▷ Tape width 12 mm
 - ▷ Reel Φ = 330 mm
- ▶ Barcode packing label
- ▶ Drop ship

Package Outline Drawing

JEDEC

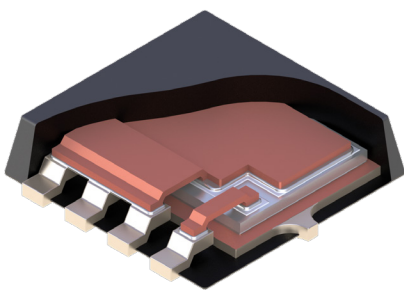


JEITA

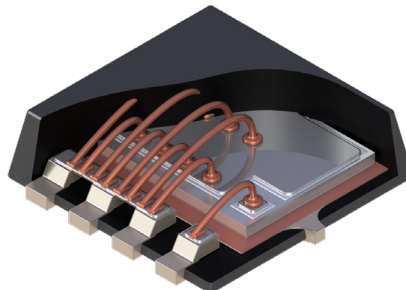


Cross-section

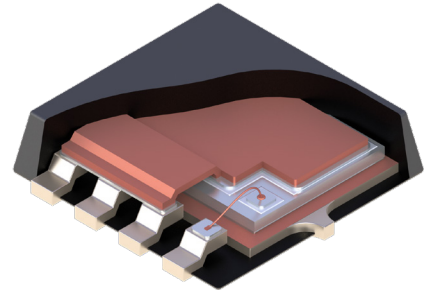
Dual Copper Clip



Multiple Copper Wires



Copper Clip and Wire



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